# TSMC Board of Directors Meeting Resolutions

**HSINCHU, Taiwan, R.O.C., Nov. 12, 2024 –** The TSMC (TWSE: 2330, NYSE: TSM) Board of Directors today held a meeting, which passed the following resolutions:

1. Approved the 2024 third quarter Business Report and Financial Statements. Third quarter consolidated revenue totaled NT$759.69 billion and net income was NT$325.26 billion, with diluted earnings per share of NT$12.54.

2. Approved the distribution of a NT$4.50 per share cash dividend for the third quarter of 2024, and set March 24, 2025 as the record date for common stock shareholders entitled to participate in this cash dividend distribution, and the ex-dividend date for the common shares shall be March 18, 2025. As required by Article 165 of Taiwan's Company Law, the shareholders' register shall be closed for five days prior to the record date (March 20 through March 24, 2025) for registration transfer, and the dividend will be paid on April 10, 2025. In addition, the ex-dividend date and the record date for entitlement to participate in this cash dividend distribution for TSMC American Depositary Shares (ADSs) will be March 18, 2025.

3. To meet long-term capacity plans based on market demand forecasts and TSMC's technology development roadmap, the Board approved capital appropriations of approximately US$15,479.95 million for purposes including: 1) Fab construction, and installation of fab facility systems; 2) Installation of advanced technology capacity, as well as 2025 R&D capital investments and sustaining capital expenditures; 3) 2025 capitalized leased assets.

4. Approved the issuance of unsecured corporate bonds in multiple offerings in the domestic market in an amount not to exceed NT$60 billion to finance TSMC's capacity expansion and/or pollution prevention related expenditures.

**About TSMC**

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's leading dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 288 distinct process technologies, and manufactured 11,895 products for 528 customers in 2023 by providing the broadest range of advanced, specialty and advanced packaging technology services. The Company is headquartered in Hsinchu, Taiwan. For more information please visit https://www.tsmc.com.

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